

Overview

The purpose of this notification is to communicate that Xilinx is adding an additional qualified assembly supplier for mature products FG(G)256, FG(G)324, QFG32 and QFG48 wire bond packages.

Description

Siliconware Precision Industry Ltd. (SPIL), a Xilinx qualified assembly supplier, is being added as a qualified assembly supplier for FG(G)256, FG(G)324, QFG32 and QFG48 packages to ensure supply continuity. All bill of material, design for the affected devices-packages with the added assembly house are identical to the current production material. Package outline are identical to the current production except a minor changed on both QFG32 and QFG48 packages which will be changed on singulation method from punching to sawing mode, pin#1 indicator from mold ejector to laser mark and the molding cavity angle of package to be vertical as shown on [Figure 1](#) and [Figure 2](#). SPIL is a qualified assembly supplier for all other Xilinx's wire bond products.

In addition, both FG(G)256 and FG(G)324 packages from the new supplier meet Xilinx's design rule, and are within Xilinx's package outline drawing. Only total package thickness has a minor change compared with current supplier as shown in [Table 1](#).

Figure 1 and Figure 2: Comparison of QFG32 and QFG48 package outline



Figure 1: Side view of QFG32 and QFG48 packages for the angle of package mold cavity

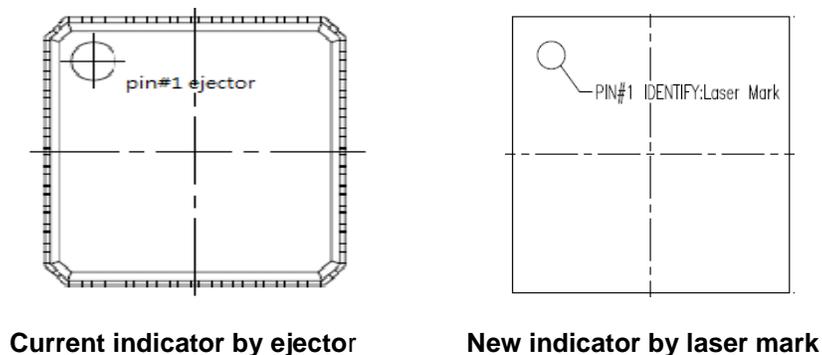


Figure 2: Top view of QFG32 and QFG48 packages for indicator & outline

Table 1: Comparison of FG(G)256 and FG(G)324 package outline

FG324 (23x23)				unit: mm	FG256 (17x17)				unit: mm
FG324 (23x23mm ²)	Xilinx	New supplier	Remark		FG256 (17x17mm ²)	Xilinx	New supplier	Remark	
Total Package Thickness (Max)	2.5	<2.5 (2.43)	Meet Xilinx Spec		Total Package Thickness (Max)	2	<2 (1.91)	Meet Xilinx Spec	

Products Affected

This change affects “XC” grade device including all versions under specification control documentation (SCD) reference.

Affected devices/packages are listed in the [Table 2](#) and [Table 3](#) below:

Table 2: Mature Products Affected on FG(G)256 and FG(G)324 packages

Device	Package	Device	Package	Device	Package	Device	Package
XC2S200	FG(G)256	XC2VP2	FG(G)256	XCR3384XL	FG(G)324	XC2C384	FG(G)324
XC2S100	FG(G)256	XC2VP4	FG(G)256	XCR3512XL	FG(G)324	XC2C512	FG(G)324
XC2S50	FG(G)256	XC95288XL	FG(G)256				

Table 3: CoolRunner-II Product Affected on QFG32 and QFG48 packages

Device	package	Device	package
XC2C32A	QFG32	XC2C64A	QFG48

Key Dates and Ordering Information

Xilinx will begin to cross ship both current and new additional supplier’s package by October 01, 2015. The qualification data is available upon request.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
06/01/2015	1.0	Initial release.

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